



Physical Interface & Carriers Japan TC Chapter

Japan Standards Summer 2021 Meetings

August 5

SEMI Japan office, Tokyo, Japan

9:00-12:00 (JST)

Official Virtual TC Chapter Meeting (OVTCCM) Notice

Per Regulations §7.5, Virtual participants (via SEMI-specified online meeting) in an Official Virtual TC Chapter Meeting shall have the same opportunity to participate in the decision-making activities of the meeting as participants physically present in the meeting room.

Participation includes, but is not limited to, the following: discussions, making presentations, viewing of all presented materials, making and seconding motions, and voting.

The PI&C Japan TC Chapter held its simulation training meeting on September 10, 2020. Now for PIC GTC, Official Virtual TC Chapter Meeting (OVTCCM) Adoption Ballot is on vote with due December 2, as the announcement sent out by SEMI HQ on November 19 [JST]. In case of both TC Chapters of NA and Japan are for the adoption of OVTCCM, this meeting will be held with OVTCCM.

AGENDA (Tentative)

1.0 Welcome / Call to Order

- 1.1 Introductions
- 1.2 Meeting Reminders (*Membership Requirement, Antitrust and Intellectual Property Reminders, Effective Meeting Guidelines*)
- 1.3 Agenda Review

2.0 Review of Previous Meeting Minutes

3.0 Liaison Report

- 3.1 North America

4.0 Staff Report

5.0 Ballot Review

- 5.1 6750, Line-Item Revision to SEMI E181-0321 - SPECIFICATION FOR PANEL FOUP FOR PANEL LEVEL PACKAGING, SEMI E181.1-0321 - SPECIFICATION FOR PANEL FOUP FOR 510 mm – 515 mm PANEL SIZE and 12 SLOTS, SEMI E181.2-0321 - SPECIFICATION FOR PANEL FOUP FOR 510 mm – 515 mm PANEL SIZE and 6 SLOTS, SEMI E181.3-0321 - SPECIFICATION FOR PANEL FOUP FOR 600 mm – 600 mm PANEL SIZE and 12 SLOTS, and SEMI E181.4-0321 - SPECIFICATION FOR PANEL FOUP FOR 600 mm – 600 mm PANEL SIZE and 6 SLOTS
- 5.2 6751, Line-Item Revision to SEMI E181.3-0321 - SPECIFICATION FOR PANEL FOUP FOR 600 mm – 600 mm PANEL SIZE and 12 SLOTS
- 5.3 6752, Line-Item Revision to SEMI E181.4-0321 - SPECIFICATION FOR PANEL FOUP FOR 600 mm – 600 mm PANEL SIZE and 6 SLOTS

6.0 Subcommittee & Task Force Reports

- 6.1 300 mm Tape Frame PI&C TF
- 6.2 Global PIC Standards Maintenance TF
- 6.3 Japan Electron Microscopy Workflow liaison TF
- 6.4 Panel Level Packaging Panel FOUP TF
- 6.5 [Liaison: 3D Packaging & Integration JA TC Chapter] Panel Level Packaging Glass Carrier TF
- 6.6 [Liaison: 3D Packaging & Integration NA TC Chapter] Panel Level Packaging Panel TF
- 6.7 [Liaison: Silicon Wafer Japan TC Chapter] JA Shipping Box TF
- 6.8 [Liaison: Silicon Wafer Japan TC Chapter / PI&C TC NA TC Chapter] International 450mm Shipping Box
- 6.9 [Liaison: Traceability] Panel Level Packaging (PLP) Glass Carrier ID Marking TF

7.0 Old Business

- 7.1 Project Period Review
- 7.2 5-Year Review

8.0 New Business

8.1 Report of Ratification Ballots Result

8.2 Discussion on the technical reasons accompanying Disapprove Votes to the following ratification ballots if any

8.2.1 6688R - New Standard: Specification for 300mm Tape Frame FOUP Load Port

8.2.2 6689R - New Standard: Specification for 300mm Tape Frame FOUP

9.0 Action Item Review

9.1 Open Action Items

9.2 New Action Items

10.0 Next Meeting and Adjournment